SBT-BGA DIRECT MOUNT, SOLDERLESS SOCKET FOR BURN-IN AND TEST APPLICATIONS

Features

- Wide temperature range (-55C to +180C).
 High current capability (up to 4A).
 Excellent signal integrity at high frequencies.
 Low and stable contact resistance for reliable production yield.
- Highly compliant to accommodate wide co-planarity variations.
 Automated probe manufacturing enables low cost and short lead time.







Description: Socket Drawing

Primary dimension units are millimeters, Secondary dimension units are [inches], Weight is in grams.

Tolerances: Hole diameters ±0.03mm [±0.001"], Pitches (from true position) ±0.025mm [±0.001"], substrate thickness tolerance ±10%, all other tolerances ±0.13mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

SBT-BGA-6026 Drawing	Material: Material <not specified=""> Finish: Woight: 7 70</not>	STATUS: Released	SHEET: 1 OF 4	REV. A
Ironwood Electronics, Inc.		DRAWN BY: S. Huang	SCALE: 3:1	
www.ironwoodelectronics.com	Weight. 7.79	FILE: SBT-BGA-6026	DATE: 7/17/2012	



Target PCB Recommendations Total thickness: 1.6mm min. Plating: Gold or Solder finish. PCB pad height: Same or higher than solder mask.

Description: RECOMMENDED PCB LAYOUT

Primary dimension units are millimeters, Secondary dimension units are [inches], Weight is in grams.

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SBT-BGA-6026 Drawing	SBT-BGA-6026 Drawing Material: Material <not specified=""></not>		SHEET: 2 OF 4	REV. A
Ironwood Electronics, Inc.	Finish: Weight: 7 70	DRAWN BY: S. Huang	SCALE: 4:1	
www.ironwoodelectronics.com	Weight. 7.79	FILE: SBT-BGA-6026	DATE: 7/17/2012	



DIM	Minimum	Maximum	
A	1.2	1.6	
A1	025	0.45	
A2	0.24	0.34	
b	0.45	0.6	
D	13.80	14.20	
D1	12.00		
D2	9.50	9.80	
E	11.80	12.20	
E1	10.00		
E2	7.40	7.70	
е	1.00 BSC		
ARRAY SIZE	13 X 11		
PIN COUNT	-	28	

- 1. Dimensions are in millimeters.
- 2.
- Interpret dimensions and tolerances per ASME Y14.5M-1994. Dimension b is measured at the maximum solder ball diameter, parallel to datum plane C. 3.
- 4.
- Datum C (seating plane) is defined by the spherical crowns of the solder balls. Parallelism measurement shall exclude any effect of mark on top surface of package. 5.

Description: Compatible BGA IC

Primary dimension units are millimeters, Secondary dimension units are [inches], Weight is in grams.

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SBT-	-BGA-6026 Drawing Material: Material <not specified=""></not>	STATUS: Released	SHEET: 3 OF 4	REV. A
Ironwood Electronics, Inc. Tele: (800) 404-0204 www.ironwoodelectronics.com	Finish: Weight: 7 70	DRAWN BY: S. Huang	SCALE: 4:1	
	www.ironwoodelectronics.com		FILE: SBT-BGA-6026	DATE: 7/17/2012



ITEM NO.	DESCRIPTION	Material
1	Open top socket lid with compression frame	7075-T6 Aluminum Alloy
2	Custom socket base with post	7075-T6 Alumium Alloy
3	Floating Guide BGA128 1mm pitch 13x11 array	PEEK Ceramic filled
4	Bottom Pogo Guide BGA128 1mm pitch 13x11 array	PEEK Ceramic filled
5	Middle Pogo Guide BGA128 1mm pitch 13x11 array	PEEK Ceramic filled
6	Pogo Pin, 1mm Pitch SBT BGA pin	
7	Test Chip 14x12mm 1mm pitch 13x11 array	High Temp FR4
8	Test PCB 13x11 array 1mm pitch	High Temp FR4
9	Nut, #0-80, SS	Stainless Steel (18-8)
10	Washer, #0 x .025", Nylon	Nylon 6/6
11	#0-80 X .375 LG, SOC HD CAP SCREW, ALLOY STL, BLK OXIDE	Alloy Steel
12	Screw, #0-80 X .1125", Flat, SS	Material <not specified=""></not>
13	Dowel Pin, 1/32" x 3/8", SS	Chrome Stainless Steel
14	Screw, #0-80 x .188", Pan, SS	Material <not specified=""></not>
15	Floating Guide Spring	Alloy Steel (SS)
16	Gap pad 2500 0.125" thick 2.7W/(m.K) thermal conductivity	Gap Pad 2500

POGO	PIN
Scale	8:1

Rev	Date	Initials	Description
А	07/17/12	SH	Original

Description: ASSEMBLY

Trans dimension units are millimeters, Secondary dimension units are [inches], Weight is in grams. <u>Tolerances:</u> Hole diameters ±0.03mm [±0.001"], Pitches (from true position) ±0.025mm [±0.001"], substrate thickness tolerance ±10%, all other tolerances ±0.13mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

S	SBT-BGA-6026 Drawing Material: Material <not specified=""></not>		STATUS: Released	SHEET: 4 OF 4	REV. A
Ironwood Electronics, Inc. Tele: (800) 404-0204 www.ironwoodelectronics.com	Finish: Weight: 7 70	DRAWN BY: S. Huang	SCALE: 3:1		
	www.ironwoodelectronics.com		FILE: SBT-BGA-6026	DATE: 7/17/2012	